

L Number	Hits	Search Text	DB	Time stamp
-	65857	83/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/08 16:02
-	166767	29/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/16 10:18
-	5993	225/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/20 14:19
-	9355	125/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/20 14:19
-	61690	451/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/20 14:19
-	150	tape near3 (bur or burr)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/08 15:59
-	1311500	semiconductor or wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/08 15:59
-	17	(tape near3 (bur or burr)) and (semiconductor or wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/20 14:22
-	5	((tape near3 (bur or burr)) and (semiconductor or wafer)) and (83/\$.ccls. or 29/\$.ccls. or 225/\$.ccls. or 125/\$.ccls. or 451/\$.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/20 14:23
-	1667037	cut or cutting	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/20 14:52
-	63	(tape near3 (bur or burr)) and (cut or cutting)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/20 14:24
-	11	((tape near3 (bur or burr)) and (cut or cutting)) and (semiconductor or wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/20 14:25
-	7	((tape near3 (bur or burr)) and (cut or cutting)) and (semiconductor or wafer) not ((tape near3 (bur or burr)) and (semiconductor or wafer)) and (83/\$.ccls. or 29/\$.ccls. or 225/\$.ccls. or 125/\$.ccls. or 451/\$.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/20 14:25

-	98065	156/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/04/20 14:35
-	9	156/\$.ccls. and (tape near3 (bur or burr))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/04/20 14:36
-	197	tape near4 (bur or burr)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/04/20 14:37
-	19	(tape near4 (bur or burr)) and (semiconductor or wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/04/20 14:40
-	1176677	sensor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/04/20 14:52
-	10	sensor and (tape near3 (bur or burr))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/04/20 14:47
-	165735	83/\$.ccls. or 29/\$.ccls. or 225/\$.ccls. or 125/\$.ccls. or 451/\$.ccls. or 156/\$.ccls.	USOCR	2003/04/20 14:50
-	11690	sensor	USOCR	2003/04/20 14:52
-	644428	cut or cutting	USOCR	2003/04/20 14:52
-	26	tape near3 (bur or burr)	USOCR	2003/04/20 14:53
-	27290	semiconductor or wafer	USOCR	2003/04/20 14:52
-	31	tape near4 (bur or burr)	USOCR	2003/04/20 14:53
-	1	(tape near4 (bur or burr)) and (semiconductor or wafer)	USOCR	2003/04/20 14:53
-	36	tape near5 (bur or burr)	USOCR	2003/04/20 14:53
-	1	(tape near5 (bur or burr)) and (semiconductor or wafer)	USOCR	2003/04/20 14:54
-	3451	sensor and (cut or cutting)	USOCR	2003/04/20 14:54
-	313	(sensor and (cut or cutting)) and (semiconductor or wafer)	USOCR	2003/04/20 14:54
-	0	((sensor and (cut or cutting)) and (semiconductor or wafer)) and (tape near4 (bur or burr))	USOCR	2003/04/20 14:54
-	9	(83/\$.ccls. or 29/\$.ccls. or 225/\$.ccls. or 125/\$.ccls. or 451/\$.ccls. or 156/\$.ccls.) and (tape near3 (bur or burr))	USOCR	2003/04/20 14:54
-	7	("4865677" "4925515" "5069738" "5228944" "5310442" "5472554" "5688354").PN.	USPAT	2003/04/21 08:27
-	0	6258198.URPN.	USPAT	2003/04/21 08:28
-	77	tape near5 (bur or burr)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/04/21 08:35

-	2	(tape near5 (bur or burr)) and sensor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/21 08:35
-	4290	((83/13) or (83/23) or (83/27) or (83/28) or (83/34) or (83/36) or (83/61) or (83/73) or (83/75) or (83/76.7) or (83/78) or (83/365) or (83/401) or (83/523) or (83/663) or (83/922) or (83/929.1)).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/21 08:55
-	4682	((156/253) or (156/267) or (156/353) or (156/522) or (156/64) or (156/250)).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/21 08:55
-	5867	((451/41) or (451/63) or (451/28) or (451/6) or (451/285) or (451/287) or (451/288) or (451/413) or (451/402)).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/21 08:56
-	0	((83/13) or (83/23) or (83/27) or (83/28) or (83/34) or (83/36) or (83/61) or (83/73) or (83/75) or (83/76.7) or (83/78) or (83/365) or (83/401) or (83/523) or (83/663) or (83/922) or (83/929.1)).CCLS.) and (((156/253) or (156/267) or (156/353) or (156/522) or (156/64) or (156/250)).CCLS.) and (((451/41) or (451/63) or (451/28) or (451/6) or (451/285) or (451/287) or (451/288) or (451/413) or (451/402)).CCLS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/21 08:56
-	29	((83/13) or (83/23) or (83/27) or (83/28) or (83/34) or (83/36) or (83/61) or (83/73) or (83/75) or (83/76.7) or (83/78) or (83/365) or (83/401) or (83/523) or (83/663) or (83/922) or (83/929.1)).CCLS.) and (((156/253) or (156/267) or (156/353) or (156/522) or (156/64) or (156/250)).CCLS.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/21 08:56
-	654047	detect or detector	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/21 09:36
-	77	tape near5 (bur or burr)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/21 09:36
-	1	(detect or detector) and (tape near5 (bur or burr))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/21 09:36
-	77447	detect or detector	USOCR	2003/04/21 09:36
-	36	tape near5 (bur or burr)	USOCR	2003/04/21 09:36
-	3	(detect or detector) and (tape near5 (bur or burr))	USOCR	2003/04/21 09:36
-	2	("4865677").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/02 13:51
-	3	("4510009" "4680079" "4696712").PN.	USPAT	2003/11/02 13:52
-	8	4865677.URPN.	USPAT	2003/11/02 13:55

-	210549	tape	USPAT	2003/11/02 13:55
-	7	4865677.URPN. and tape	USPAT	2003/11/02 14:13
-	2	("6116988").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/02 14:14
-	210549	tape and tape	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/02 14:14
-	1	tape and ("6116988").PN.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/02 14:30
-	2	("5422163").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/02 14:30
-	1	tape and ("5422163").PN.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/02 14:45
-	1	(tape and ("5422163").PN.) and cut	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/02 14:46
-	3	("3909915").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/02 14:47
-	0	("3909915").PN.) and tape and cut	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/02 14:47
-	1	("3909915").PN.) and tape	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/02 14:47
-	2	("5688354").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/02 14:47
-	1	("5688354").PN.) and tape and cut	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/02 14:48
-	0	((("5688354").PN.) and tape and cut) and burr	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/02 14:52
-	6	((("4510009") or ("4696712") or ("4680079")).PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/02 14:53

-	1670	tape and cut and burr	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/11/02 14:53
-	0	((("4510009") or ("4696712") or ("4680079")).PN.) and (tape and cut and burr)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/11/02 14:53
-	172177	29/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/04/16 10:18
-	27332	tape near3 (remove or removing or cut or cutting)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/04/16 10:19
-	348610	wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/04/16 10:19
-	3433833	sensor or detect or sensing or sensed or detecting or detected	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/04/16 10:19
-	1364	(tape near3 (remove or removing or cut or cutting)) and wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/04/16 10:20
-	90	((tape near3 (remove or removing or cut or cutting)) and wafer) and 29/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/04/16 10:20
-	22	((tape near3 (remove or removing or cut or cutting)) and wafer) and 29/\$.ccls.) and (sensor or detect or sensing or sensed or detecting or detected)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/06/08 16:04
-	2173	backgrinding or (back near2 grinding)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/04/16 10:22
-	6	((tape near3 (remove or removing or cut or cutting)) and wafer) and 29/\$.ccls.) and (backgrinding or (back near2 grinding))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/04/16 10:22
-	152025	438/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/06/08 15:59
-	3710	438/\$.ccls.	USOCR	2004/06/08 16:03
-	162	tape near3 (bur or burr)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/06/08 16:03
-	26	tape near3 (bur or burr)	USOCR	2004/06/08 16:03

-	1498239	semiconductor or wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USOCR	2004/06/08 16:03
-	27277	semiconductor or wafer	USOCR	2004/06/08 16:02
-	0	sensor or sensed or sensing or detect or detected or detecting	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/08 16:01
-	5166058	sensor or sensing or sensed or detect or detected or detecting or determine or determined or determining or encoder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/08 16:02
-	27277	semiconductor or wafer	USOCR	2004/06/08 16:02
-	1498239	semiconductor or wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USOCR	2004/06/08 16:03
-	26	tape near3 (bur or burr)	USOCR	2004/06/08 17:28
-	162	tape near3 (bur or burr)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USOCR	2004/06/08 16:07
-	3710	438/\$.ccls.	USOCR	2004/06/08 16:03
-	152025	438/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/08 16:03
-	1383	((tape near3 (remove or removing or cut or cutting)) and wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USOCR	2004/06/08 16:08
-	43	((tape near3 (remove or removing or cut or cutting)) and wafer)	USOCR	2004/06/08 16:04
-	588449	sensor or sensing or sensed or detect or detected or detecting or determine or determined or determining or encoder	USOCR	2004/06/08 16:07
-	2	(tape near3 (bur or burr)) and 438/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USOCR	2004/06/08 16:07
-	0	(tape near3 (bur or burr)) and 438/\$.ccls.	USOCR	2004/06/08 16:08
-	106	438/\$.ccls. and tape	USOCR	2004/06/08 16:08
-	689	(tape near4 (remove or removing or cut or cutting)) and (tape and 438/\$.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USOCR	2004/06/08 16:10
-	9	(tape near4 (remove or removing or cut or cutting)) and (438/\$.ccls. and tape)	USOCR	2004/06/08 16:10
-	21	438/\$.ccls. and (bur or burr)	USOCR	2004/06/08 16:33
-	775	438/\$.ccls. and (bur or burr)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/08 16:35

-	26	(438/\$.ccls. and (bur or burr)) and ((tape near4 (remove or removing or cut or cutting)) and (tape and 438/\$.ccls.))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USOCR	2004/06/08 16:35
-	14	tape near2 (bur or burr)		2004/06/08 17:29
-	109	tape near2 (bur or burr)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/06/08 17:29